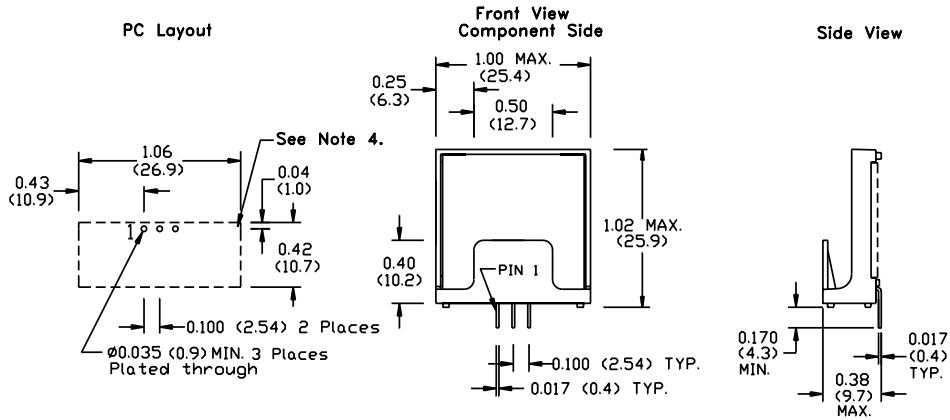
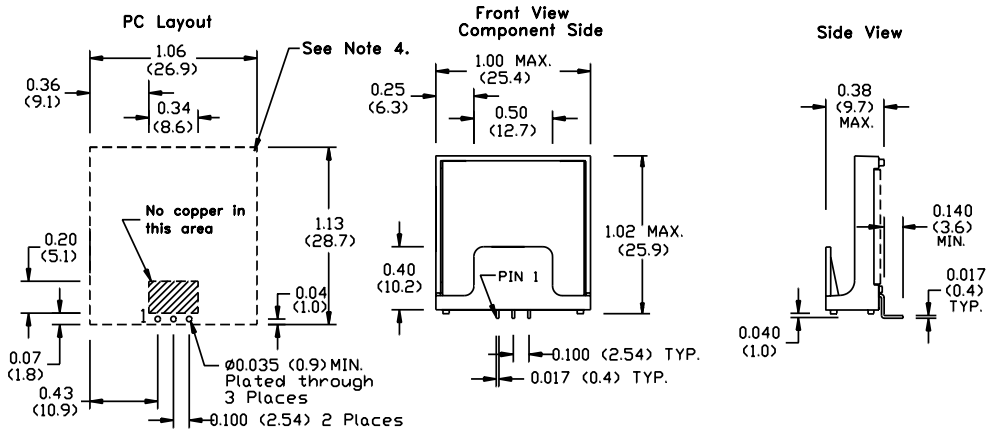


PACKAGE INFORMATION AND DIMENSIONS

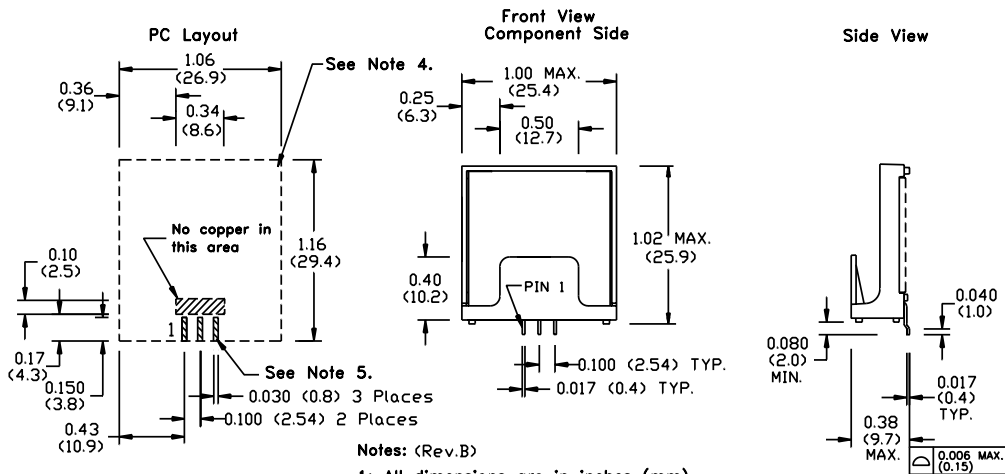
Vertical Through-Hole Mount (Suffix N & P)



Horizontal Through-Hole Mount (Suffix A & D)



Surface Mount (Suffix C & E)

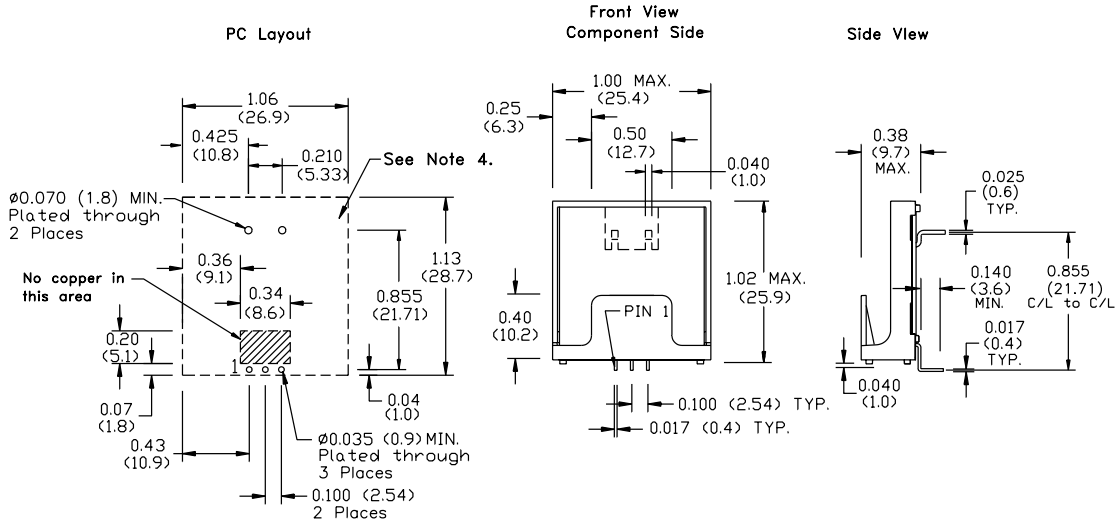


Notes: (Rev.B)

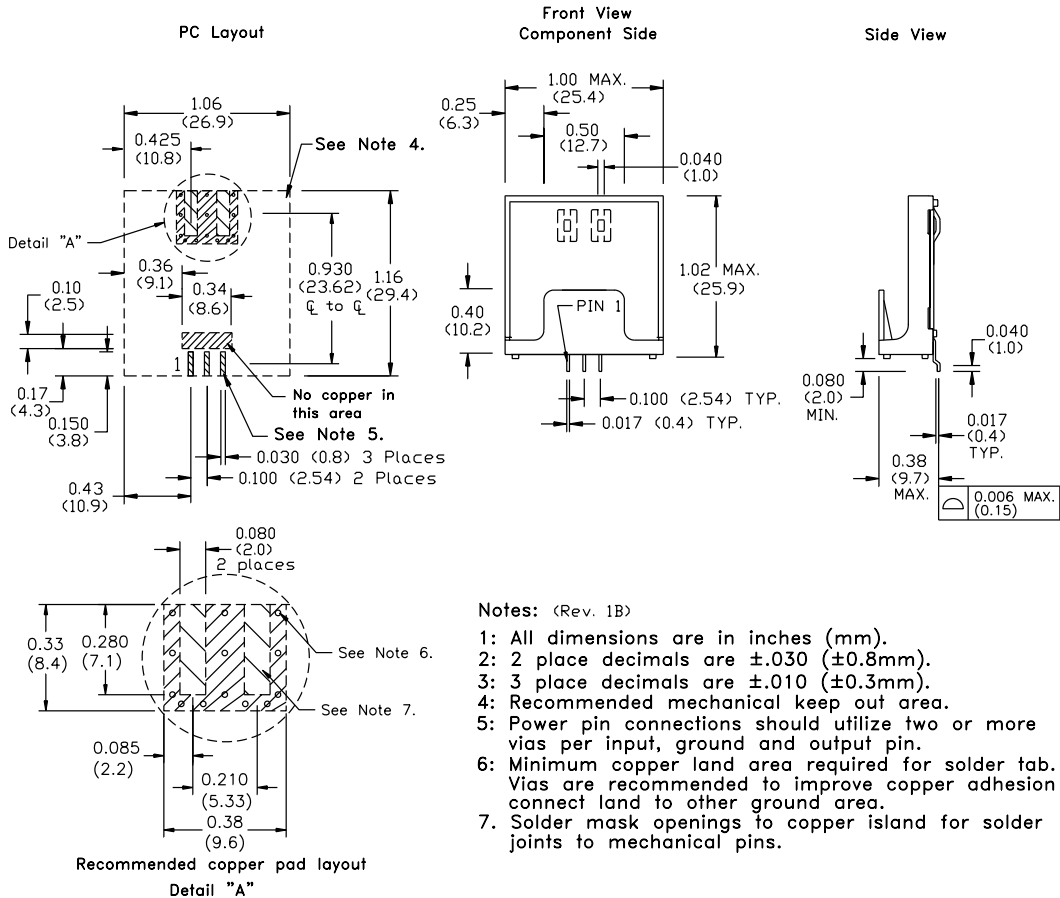
- 1: All dimensions are in inches (mm).
- 2: 2 place decimals are ± 0.030 ($\pm 0.8\text{mm}$).
- 3: 3 place decimals are ± 0.010 ($\pm 0.3\text{mm}$).
- 4: Recommended mechanical keep out area.
- 5: Power pin connections should utilize two or more vias per input, ground and output pin.

PACKAGE INFORMATION AND DIMENSIONS

Horizontal Through -Hole Mount (Suffix "M")



Surface Mount (Suffix L)



Notes: (Rev. 1B)

- 1: All dimensions are in inches (mm).
- 2: 2 place decimals are ± 0.030 (± 0.8 mm).
- 3: 3 place decimals are ± 0.010 (± 0.3 mm).
- 4: Recommended mechanical keep out area.
- 5: Power pin connections should utilize two or more vias per input, ground and output pin.
- 6: Minimum copper land area required for solder tab. Vias are recommended to improve copper adhesion or connect land to other ground area.
- 7: Solder mask openings to copper island for solder joints to mechanical pins.